

### **FEATURES**

Low Leakage Current

High Efficiency

Heatsink Design

Halogen-Free According to IEC 61249-2-21 Definition





# Cathode & Anode 2 & Heatsink Anode 2 Schematic Symbol

### **MECHANICAL DATA**

Case:TO-277B

| Molding Compound Meets UL 94 V-0 Flammability

Moisture Sensitivity: Level 1, Per J-STD-020

### **APPROVALS**

RoHS Compliance with 2011/65/EU

HF Compliance with IEC61249-2-21:2003

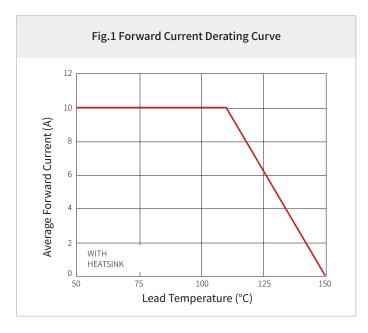
# MAXIMUM RATINGS ( $T_A = 25$ °C)

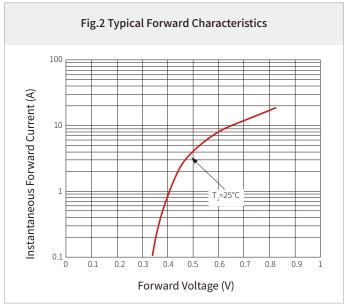
Parameter	Symbol	Value	Unit
Maximum Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	100	V
Maximum Average Forward Rectified Current	I <sub>F(AV)</sub>	10	А
Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed On Rated Load Per Diode	I <sub>FSM</sub>	200	А
Maximum Instantaneous Forward Voltage Per Diode (Note 1) $T_J$ =25°C , $I_F$ =10A	$V_{\scriptscriptstyle F}$	0.65	V
Maximum Instantaneous Reverse Current Per Diode At Rated Reverse Voltage T <sub>J</sub> =25°C	I <sub>R</sub>	100	μΑ
Typical Thermal Resistance	R <sub>eJL</sub>	11	°C/W
Operating Junction And Storage Temperature Range	$T_{J}, T_{STG}$	-55 to 150	°C

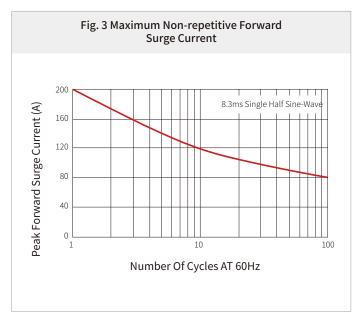
Note 1: Pulse Test with Pulse Width=300µs, 1% Duty Cycle

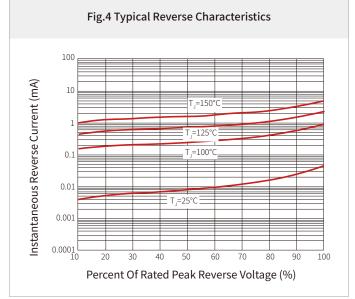


### **CHARACTERISTIC CURVES**

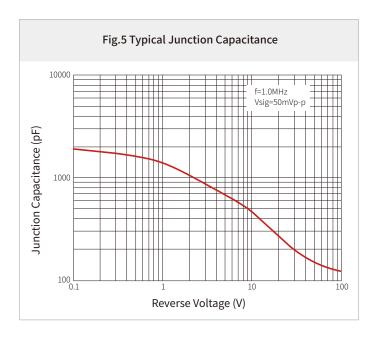






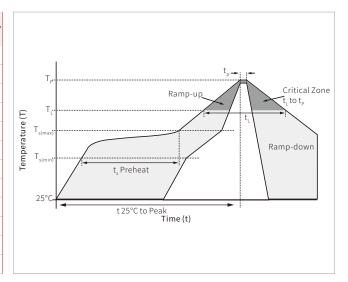






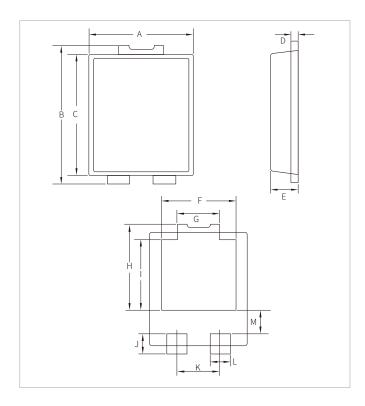
# **SOLDERING PARAMETERS**

	Reflow Condition	Lead-free assembly
	Temperature Max $(T_{s(min)})$	150°C
Pre Heat	Temperature Max (T <sub>s(max)</sub> )	200°C
	Time (min to max) $(t_s)$	60 – 180 secs
Average ran	3°C/second max	
	$T_{S(max)}$ to $T_L$ - Ramp-up Rate	
Reflow	Temperature (T <sub>L</sub> ) (Liquidus)	217°C
Renow	Time (min to max) $(t_L)$	60 – 150 seconds
Peak Temperature (T <sub>P</sub> )		260°C
Time within 5°C of actual peak Temperature (t <sub>p</sub> )		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T <sub>P</sub> )		8 minutes max.
Do not exceed		260°C



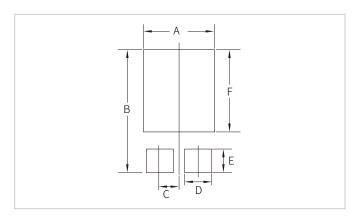


## **TO-277B PACKAGE INFORMATION**



Ref.	Millimeters		Inches	
ici.	Min.	Max.	Min.	Max.
А	4.00	4.60	0.157	0.181
В	6.20	6.80	0.244	0.268
С	5.50	6.00	0.216	0.236
D	0.25	0.40	0.010	0.016
Е	1.05	1.35	0.041	0.053
F	3.00	3.50	0.118	0.138
G	1.70	2.00	0.067	0.079
Н	4.20	4.50	0.165	0.177
I	3.52Nom		0.139Nom	
J	0.85	1.10	0.033	0.043
К	1.86Nom		0.073Nom	
L	0.80	1.00	0.031	0.039
М	1.10	1.40	0.043	0.055

# **RECOMMENDED PAD LAYOUT DIMENSIONS**



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
А	3.40	-	0.134	-
В	6.90		0.2	272
С	0.95		0.037	
D	1.30	-	0.051	-
E	1.30	-	0.051	-
F	4.60	-	0.181	-

# **ORDERING INFORMATION**

Part Number	Component Package	QTY/Reel	Reel Size
TSP10100	TO-277B	5000PCS	13"



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